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(12) **United States Design Patent**
Hsieh et al.

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(54) **HEADPHONE**

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(**) Term: **15 Years**

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(52) **U.S. Cl.**
USPC **D14/205**

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USPC D14/205, 224, 221, 222; D29/112; 2/209; 181/129, 130, 135; 379/430, 431; 381/380, 381, 345, 424, 309, 370, 374, 381/371, 379, 376, 386, 389; 455/90.3, 455/575.1, 569.1
CPC H04R 1/1066; H04R 1/1016; H04R 5/033; H04R 5/0335; H04R 5/02; H04R 5/00
See application file for complete search history.

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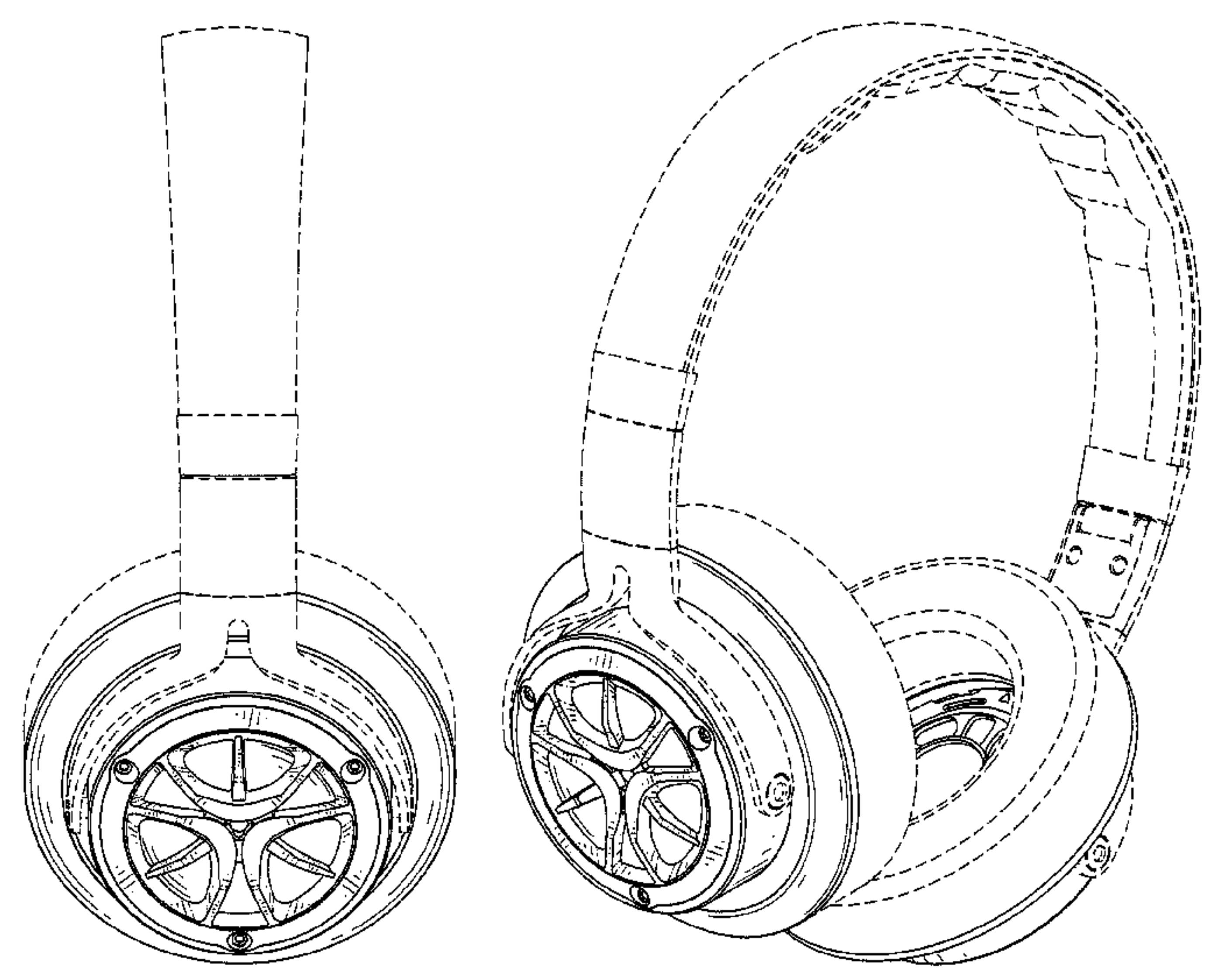
(57) **CLAIM**

The ornamental design for a headphone, as shown and described.

DESCRIPTION

FIG. 1 is a front elevational view of a headphone showing our new design;
FIG. 2 is a rear elevational view thereof;
FIG. 3 is a left side elevational view thereof;
FIG. 4 is a right side elevational view thereof;
FIG. 5 is a top plan view thereof;
FIG. 6 is a bottom plan view thereof; and,
FIG. 7 is a perspective view thereof.

1 Claim, 7 Drawing Sheets



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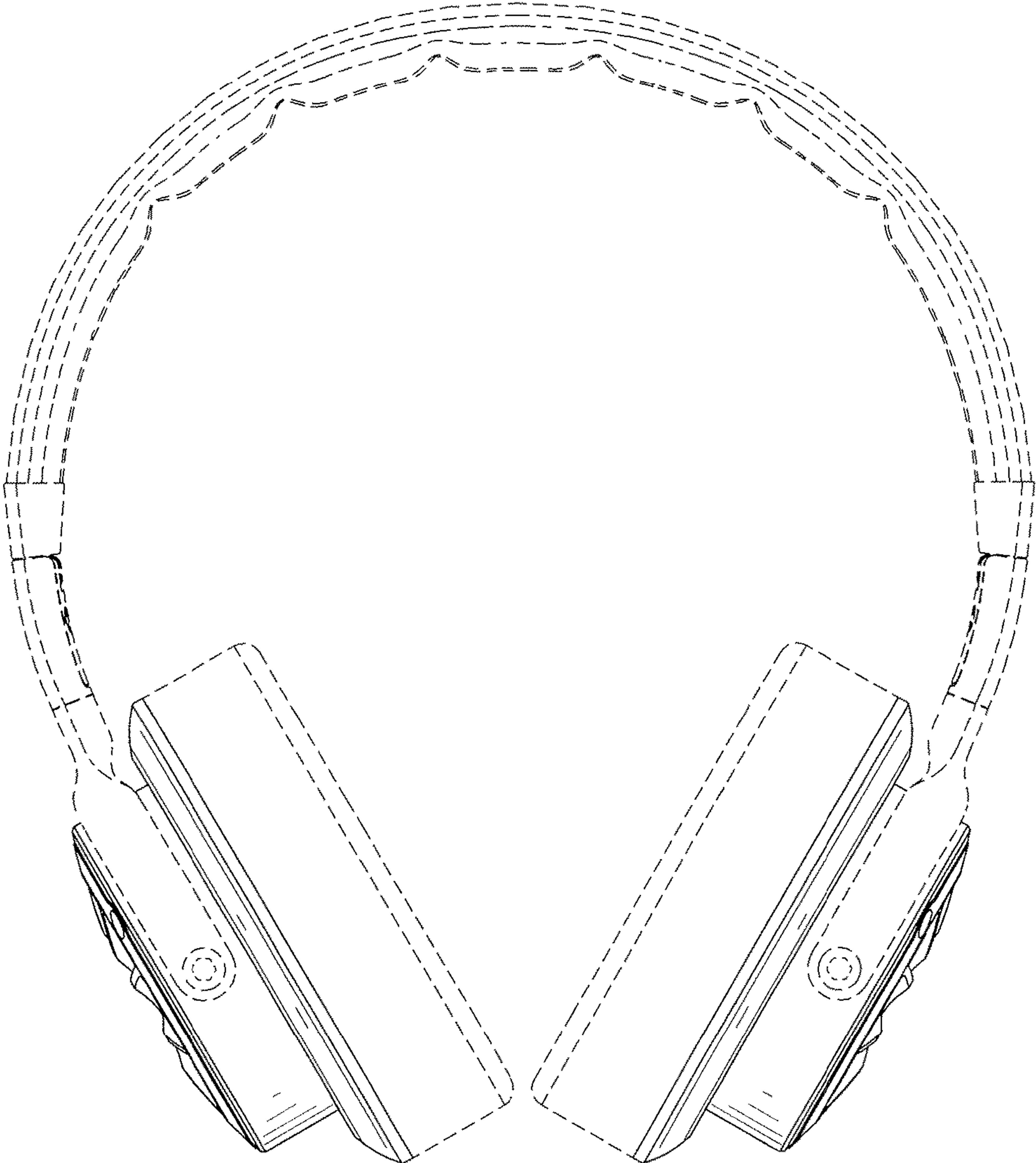


FIG. 1

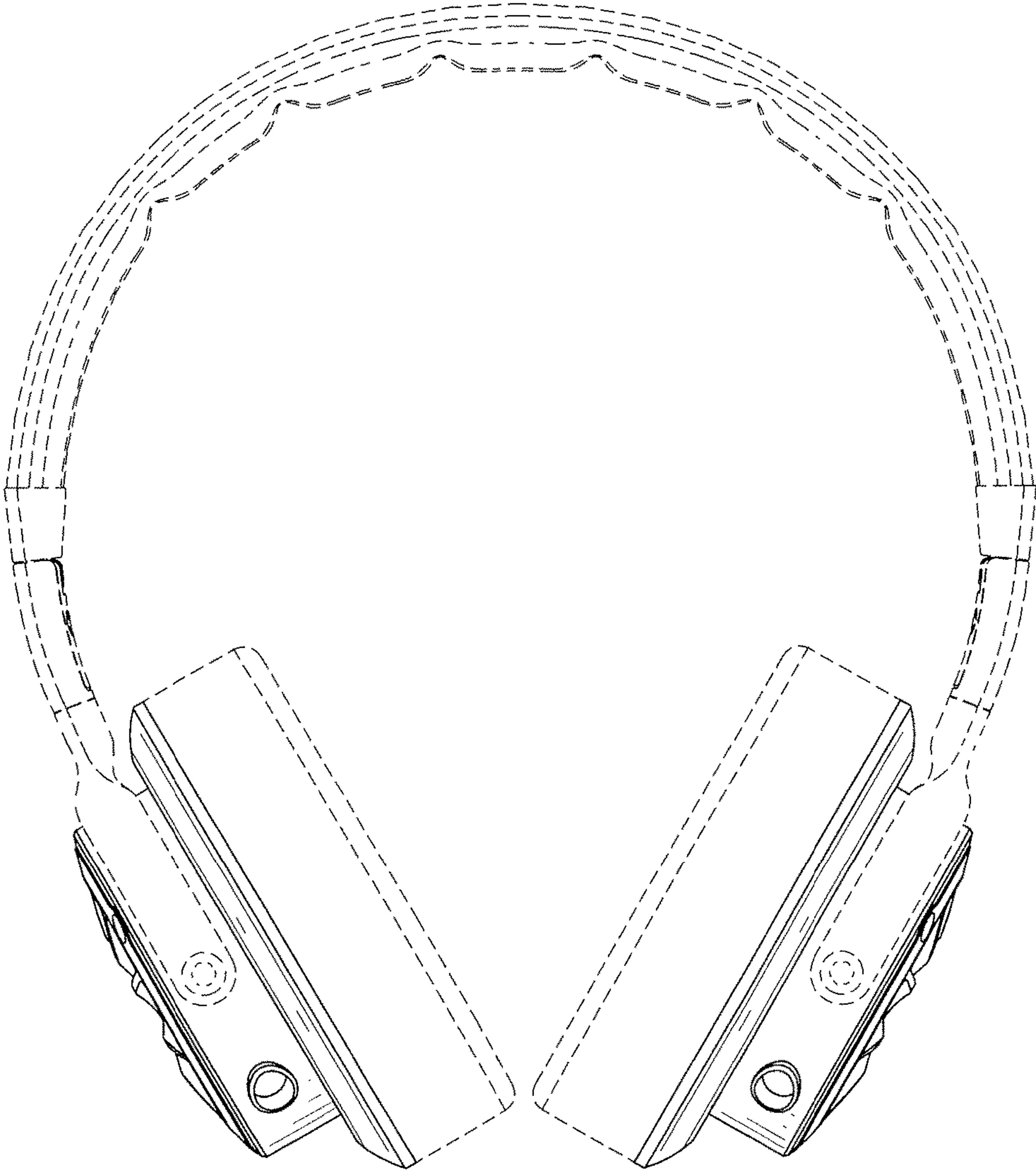


FIG. 2

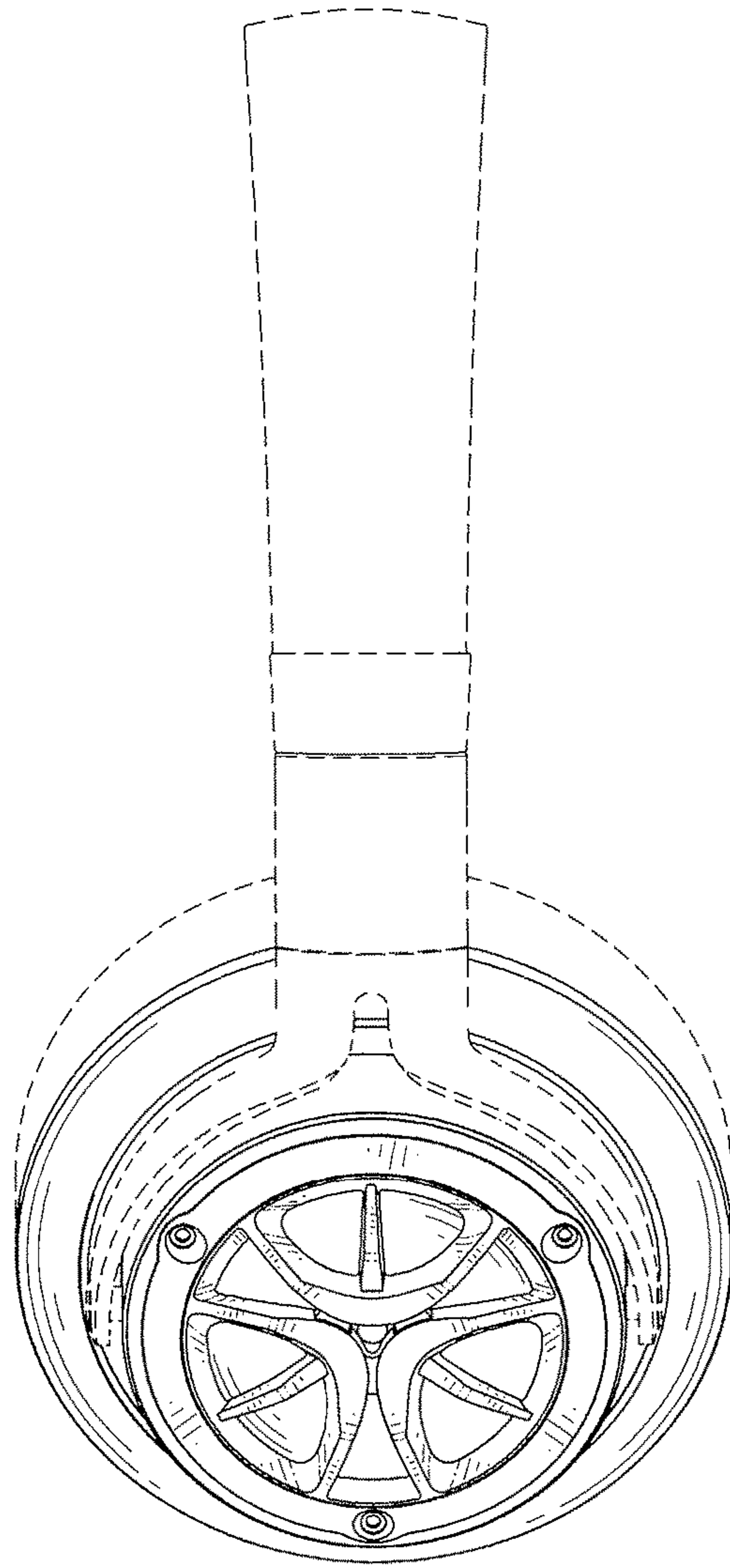


FIG. 3

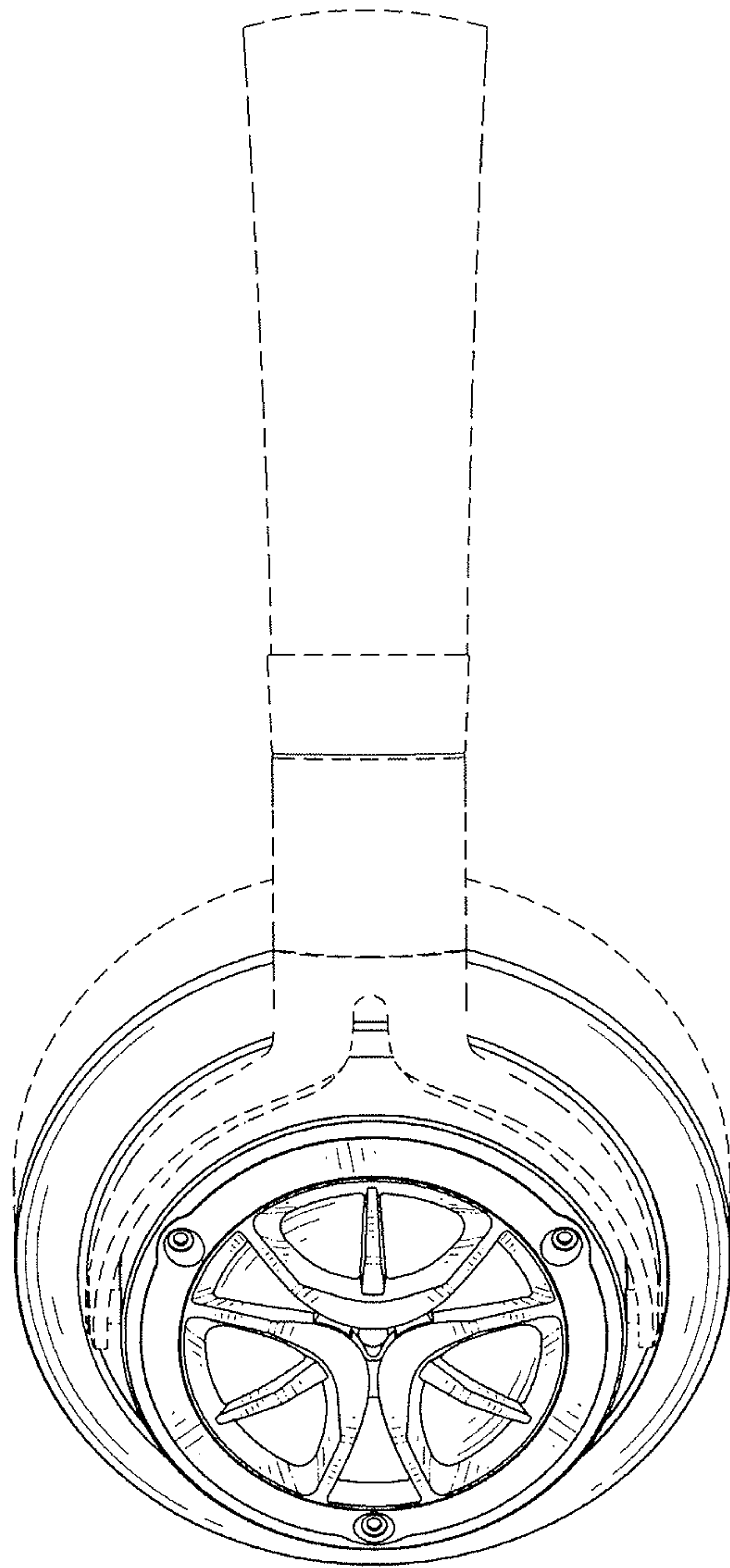


FIG. 4

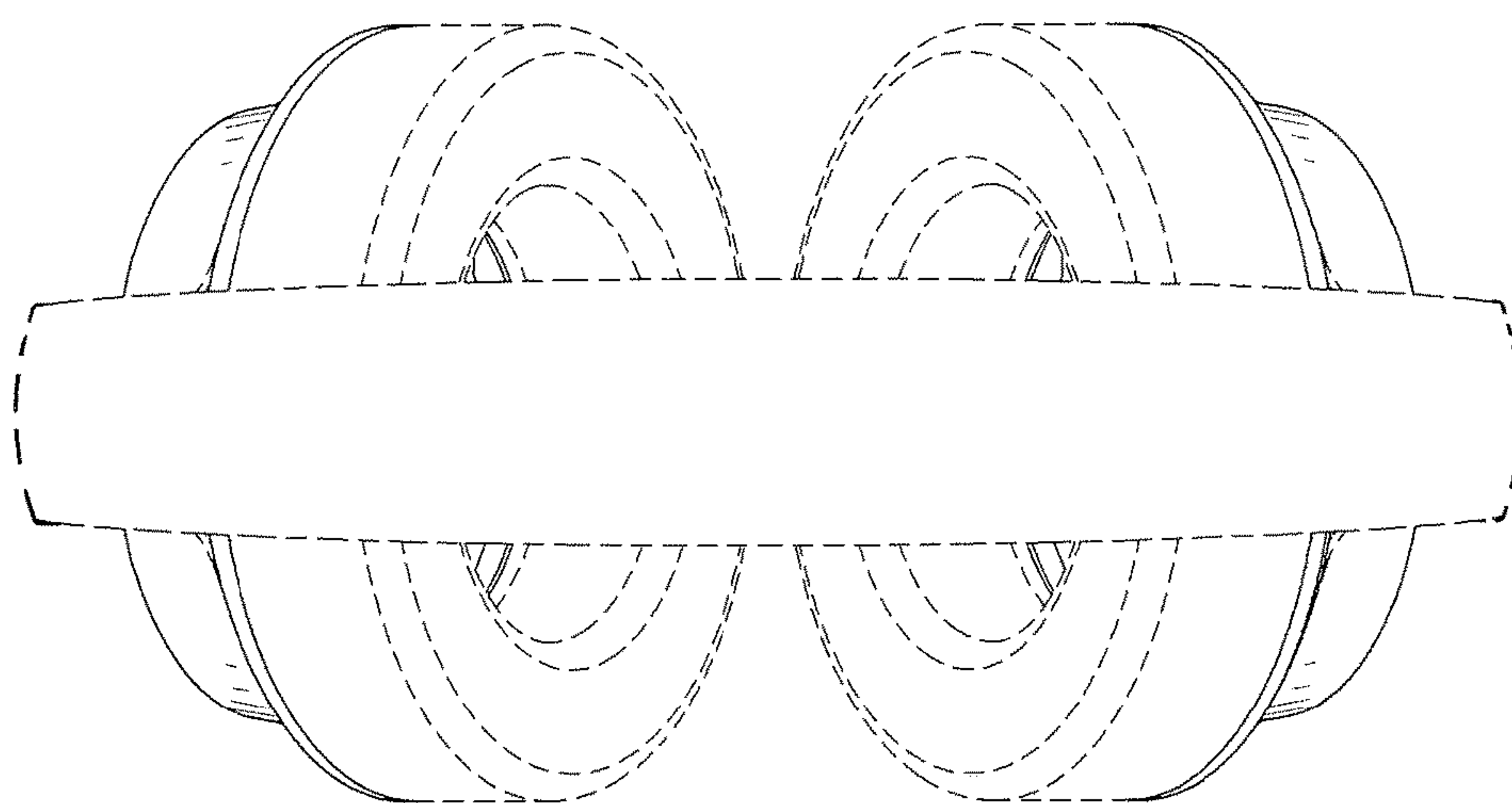


FIG. 5

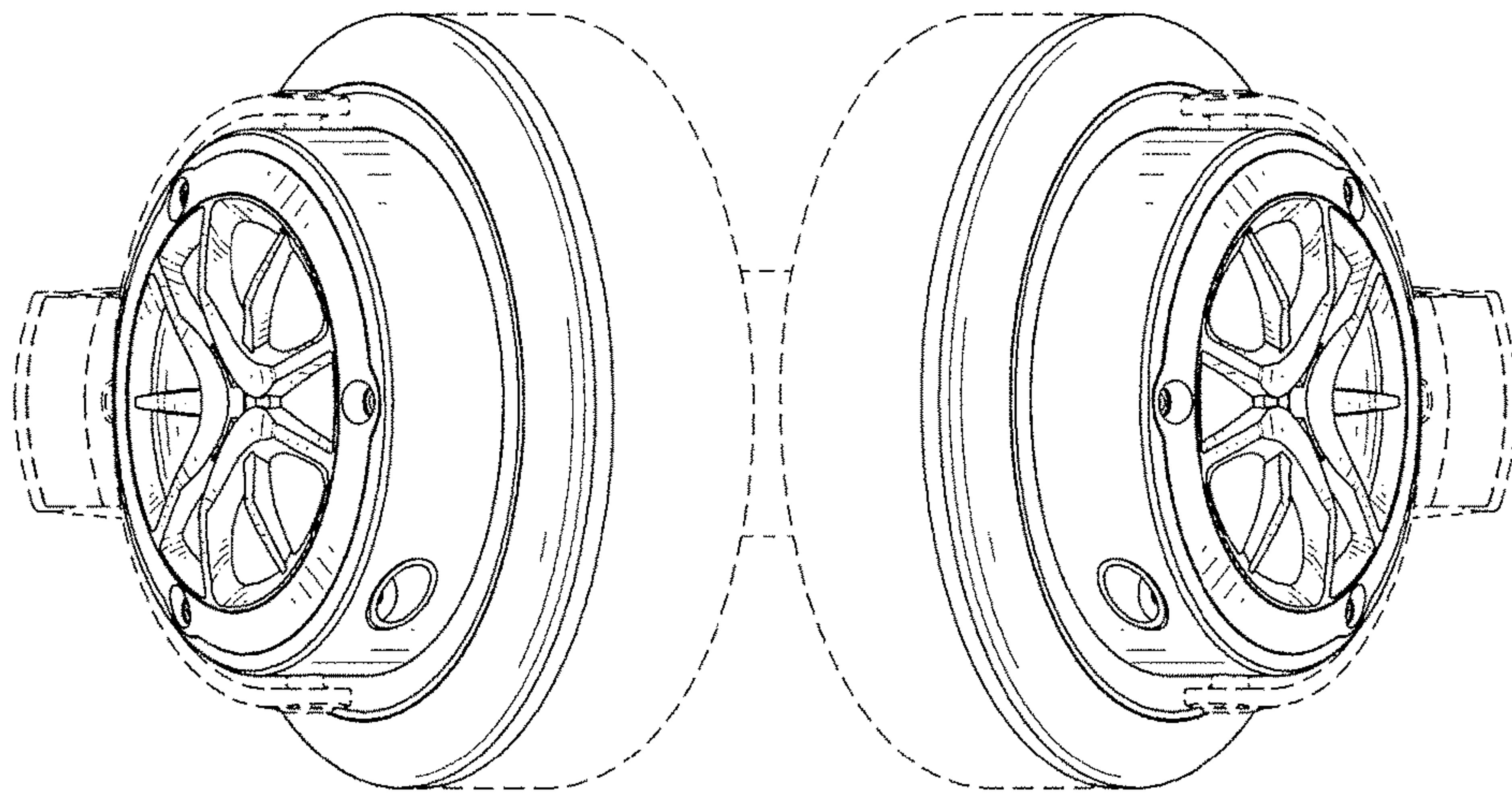


FIG. 6

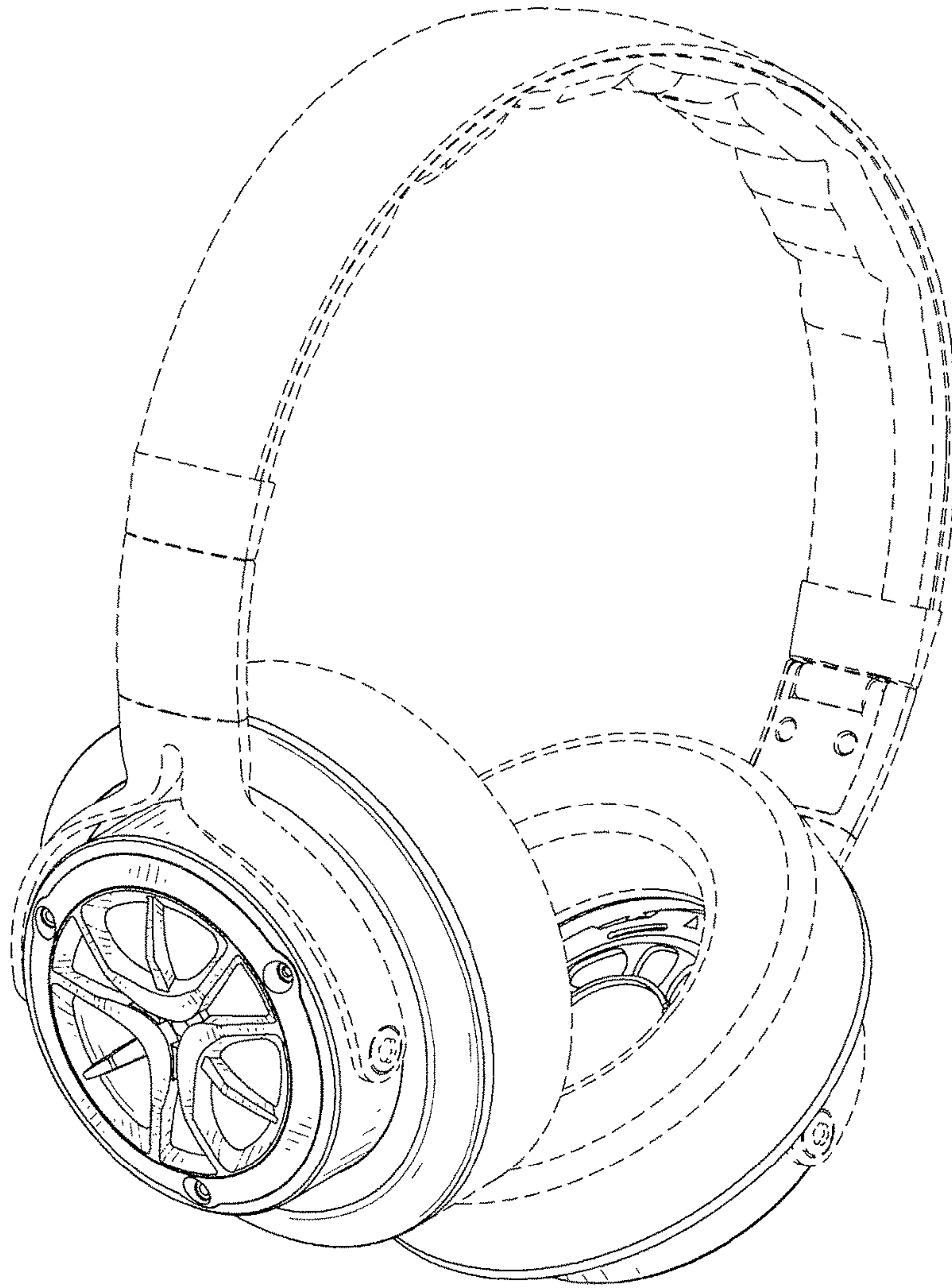


FIG. 7